

# Technology for cutting glass & sapphire



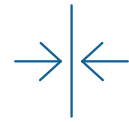
High speed



Irregular shapes



Ultra-high precision results



Thin glass & sapphire

## Features

- Ultra-fast thin (30  $\mu\text{m}$  to 2 mm) glass & sapphire cutting
- High process speed up to 1000 mm/s
- Irregular shapes
- Inner and outer contours
- Easy breaking for non-tempered glass and self-breaking for tempered glass

- High bending strength
- Low chipping <10  $\mu\text{m}$
- Smooth side walls after breaking, Ra <1  $\mu\text{m}$



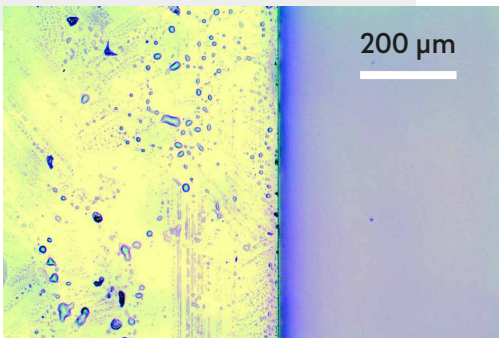
# Solutions for system integrators

- Optimized for 1028-1064 nm wavelength (515-532 on request)
- Sealed monolithic housing
- Integrated monitored linear axis with 15 mm travel (eliminates need for external Z axis)
- Optional external Machine vision unit

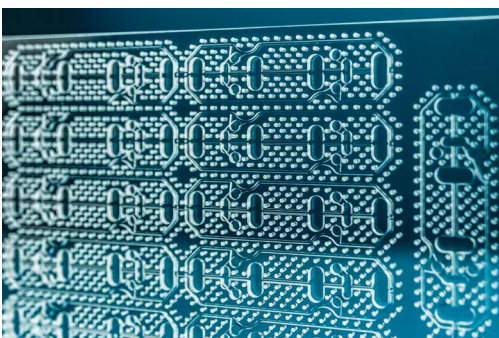
- Optional alignment module for adjustment
- Packages include optical module and technology license
- Dimensions HxWxD: 395x240x95 mm



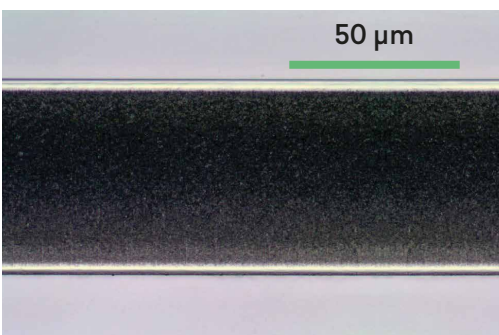
Glass Cutting



Tempered glass 0.55 mm thickness

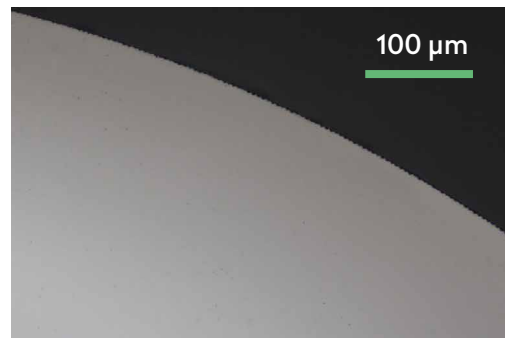


Glass Carrier Wafers

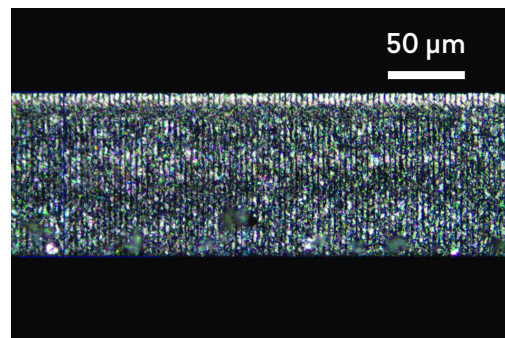


Tempered glass 0.55 mm thickness

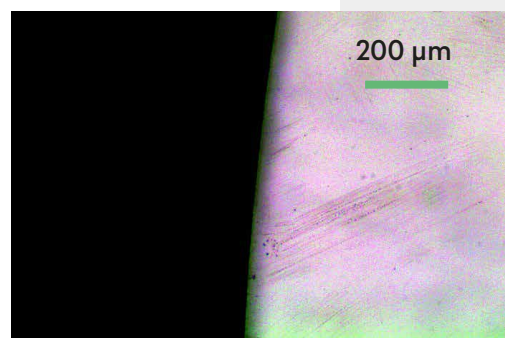
## Transparent material cutting samples



0.6 mm sapphire cutting



Sapphire 0.1 mm thickness. Side view



Sapphire 0.325 mm thickness. Top view